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Product Change Notification - KSRA-20EIEO658   (Convert To PDF)

Date:

02 Aug 2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers

Affected CPNs:

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Notification subject:

CCB 2978 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN-S package at NSEB assembly site

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach and G770HCD or G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		**Post Change**
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	C194		C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
September 02, 2018 (date code: 1836)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2017						-->	**August 2018**					**September 2018**				
Workweek	26	27	28	29	30	31		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date			X														
Qual Report Availability								X									
Final PCN Issue Date								X									
Estimated Implementation													X				

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:
July 13, 2017: Issued initial notification.
August 02, 2018: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on September 02, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-20EIEO658_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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